

GRINDING APPARATUS

ABSTRACT

A grinding apparatus acquires a ground-off quantity of a wafer that is being ground, by subtracting a vertical length $|(H_0 - H_1)|$ by which grindstones are worn that is acquired by an upper surface height measuring instrument that is selectively lifted and lowered in unison with a grinding mechanism from a distance $|(Z_0 - Z_1)|$ by which the grinding mechanism is lowered that is acquired by a Z-axis encoder coupled with the grinding mechanism. Since the ground-off quantity of the wafer is acquired using the upper surface height measuring instrument and the Z-axis encoder, it is not necessary to determine the ground-off quantity of the wafer with use of only an upper surface height measuring instrument disposed on a foundation, as has been customary heretofore.

[FIG. 4]